GOMACTECH 2025

PASADENA CONVENTION CENTER, PASADENA, CA
MARCH 17 - 20, 2025

	GOMACTech Timetable	Ballroom Foyer	Exhibit Hall B	Ballroom A	Ballroom B	Ballroom C	Ballroom D-E	Ballroom H	Ballroom G	Ballroom F	Conference Building Room 104	Conference Building Room 105	Conference Building Room 107	GOMACTech Timetable	
Sunday, March 16	6:00–8:00 pm	......	**Trusted Supplier Opening Networking Reception (All attendees)**	......										6:00–8:00 pm	**Sunday, March 16**
Monday, March 17	8:00 am–12:00 pm	**Registration (7:00 am–6:00 pm)**	......	......	......	......	......	......	......	......	......	**On-Shore Advanced Packaging Capabilities Part Two (8:00 am–12:00 pm)**	**Trusted Supplier Industry Day (8:00 am–5:00 pm)**	8:00 am–12:00 pm	**Monday, March 17**
	1:00–5:00 pm	......	......	......	......	......	......	......	......	......	**From Idea to Impact Workshop: Navigating the Startup Ecosystem (1:30–4:30 pm)**	......		1:00–5:00 pm	
	5:00–7:00 pm	**Welcome Reception - All Attendees (Conference Building Foyer)** intel capital												5:00–7:00 pm	
Tuesday, March 18	8:00–10:15 am	**Registration (7:00 am–5:00 pm)**	**Breakfast (7:00–7:45 am) Exhibitor Move-in (8:30–11:30 am)**	......	......	......	**Plenary Session**	......	......	......	......	......	......	8:00–10:15 am	**Tuesday, March 18**
	BREAK 10:15–10:30am			**BREAK (Exhibit Hall)**										BREAK 10:15–10:30 am	
	10:30 am–12:00 pm			......	......	......	**Plenary Session**	......	......	......	......	......	......	10:30 am–12:00 pm	
	LUNCH 12:00–1:30 pm		......	**LUNCH BUFFET (Exhibit Hall)** YES.tech										LUNCH 12:00–1:30 pm	
	1:30–3:10 pm		**Exhibits Open Exhibit Hall A&B (12:00–8:00 pm)**	**Session 1** UWBGS I: Power	**Session 2** Advanced Packaging Research and Innovative Technology Approaches	**Session 3** Advanced RF Components & Devices	**Session 4** Protection Methods and Applications	**Session 5** Digital I	**Session 6** Radiation Hardened Technologies and Systems	......	......	......	......	1:30–3:10 pm	
	BREAK 3:10–3:30 pm			**BREAK (Exhibit Hall)**										BREAK 3:10–3:30 pm	
	3:30–5:10 pm			**Session 7** UWBGS II: RF	**Session 8** Advances in Modeling for Package Design	**Session 9** Algorithms and EDA Tools for Modeling, Analysis & Fabrication	**Session 10** Testing and Verification	**Session 11** Digital II	**Session 12** SWIR and MWIR Imagers	......	......	......	......	3:30–5:10 pm	
	6:00–8:00 pm	......	......	**EXHIBITOR RECEPTION (Exhibit Hall)**										6:00–8:00 pm	
Wednesday, March 19	8:20–10:00 am	**Registration (7:00 am–5:00 pm)**	**Breakfast (7:30–8:30 am)**	**Session 13** Next Generation Microelectronics	**Session 14** Packaging Ecosystem: Roadmaps and Future Directions	**Session 15** Transition of Compound Semiconductor Technology and Photonics	**Session 16** Design of Secure Systems	**Session 17** LTLT	**Session 18** SPCE	**Session 19** Photonic Integrated Circuits at Visible Wavelengths	......	......	......	8:20–10:00 am	**Wednesday, March 19**
	BREAK 10:00–10:30 am		**Exhibits Open Exhibit Hall A&B (9:00 am–4:00 pm)**	**BREAK (Exhibit Hall)**										BREAK 10:00–10:30 am	
	10:30 am–12:10 pm			**Session 20** Quantum Architecture and Design	**Session 21** Chiplets: Technologies and Standards	**Session 22** COFFEE	**Session 23** Models and Measurements	**Session 24** Analog and Mixed-Signal Circuits	**Session 25** GaN Power Electronics	**Session 26** Photonics Applications	......	......	**PANEL:** ***Global Chip Traceability: Securing the Semiconductor Supply Chain for a Resilient Future***	10:30 am–12:10 pm	
	LUNCH 12:10–1:30 pm			**LUNCH BUFFET (Exhibit Hall)** YES.tech										LUNCH 12:10–1:30 pm	
	1:30–3:10 pm			**Session 27** Quantum Measurement and Applications	**Session 28** SHIP-STEAMpipe	**Session 29** Filter Technology	**Session 30** Side Channels and Signal Analysis	**Session 31** OPTIMA	**Session 32** Advanced Power Electronics	**Session 33** PIC-Based Processing and Computing	......	......	**PANEL:** ***Microelectronics Transition Activities/Challenges within Program Offices***	1:30–3:10 pm	
	BREAK 3:10–3:30 pm			**BREAK (Exhibit Hall)**										BREAK 3:10–3:30 pm	
	3:30–5:10 pm			**Session 34** In Memory/Sensor Computation	**Session 35** SHIP – Multi-Chip Packaging	**Session 36** WARP	**Session 37** Privacy Enhancing Technologies (PET)	**Session 38** Radiation Hardened by Design (RHBD)	**Session 39** Solid State Technology for High Voltage Pulsed Power Sources	......	......	......	**PANEL:** ***Workforce Development and Mentorship***	3:30–5:10 pm	
	6:00–10:00 pm	**WEDNESDAY EVENING SOCIAL - The Wizarding World of Harry Potter™** (Buses begin leaving at 5:00 pm)												6:00–10:00 pm	
Thursday, March 20	8:20–10:00 am	**Registration (8:00 am–3:00 pm)**	**Breakfast (8:00–8:30 am)**	**Session 40** Applications of AI/ML	**Session 41** MINITHERMS3D	**Session 42** ELGAR	**Session 43** Multidisciplinary Approaches to Security	**Session 44** New Materials for High Performance Microsystems	**Session 45** Radiation Hard Characterization Mechanisms	......	......	......	**PANEL:** ***Microelectronics Innovation – Strategies for Dual-Use Applications in US Government*** (8:30 am)	8:20–10:00 am	**Thursday, March 20**
	BREAK 10:00–10:30 am		......	**BREAK (Ballroom Foyer)**										BREAK 10:00–10:30 am	
	10:30 am–12:00 pm		**Poster Session (10:30 am–12:00 pm)**	......	......	......	......	......	......	......	......	......	**PANEL:** ***T&AM MPW Program***	10:30 am–12:00 pm	
	LUNCH 12:00–1:30 pm		......	**LUNCH BUFFET (Exhibit Hall A&B)** YES.tech										LUNCH 12:00–1:30 pm	
	1:30–3:10 pm		......	**Session 46** THREADS	**Session 47** HOTS I	**Session 48** Power Amplifiers I	**Session 49** Artificial Intelligence and Machine Learning	**Session 50** Characterization – Advances in Materials	......	......	......	......	**PANEL:** ***USG Microelectronics Advanced Packaging Landscape***	1:30–3:10 pm	
	BREAK 3:10–3:30 pm		......	**BREAK (Ballroom Foyer)**										BREAK 3:10–3:30 pm	
	3:30–5:10 pm	......	......	......	**Session 51** HOTS II	**Session 52** Power Amplifiers II	**Session 53** Cryptography Advancements and Challenges	**Session 54** RF Technologies for Directed Energy	......	......	......	......	**PANEL:** ***California DREAMS Hub/MOSIS 2.0***	3:30–5:10 pm	